IN THE CLAIMS

11. (Canceled)

12. (Amended) A chemical mechanical polishing monitoring system, comprising:

a peristaltic pump operable to deliver a slurry to a polishing pad;

a controller operable to send a drive voltage to the peristaltic pump based on a desired volumetric flow rate for the slurry;

a rotation sensing device coupled to a rotating shaft of the peristaltic pump and operable to sense a rotation of the peristaltic pump, the rotation sensing device further operable to generate a voltage indicative of the rotation of the peristaltic pump; and

a computer coupled to the rotation sensing device and the controller, the computer operable to:

receive the drive voltage from the controller;

receive the voltage from the rotation sensing device; and

compare the voltage to a threshold voltage that is based, in part, on the drive voltage in order to monitor the peristaltic pump during use;

~~The system of Claim 11,~~ wherein the computer is further operable to generate a message based on the comparison.

13- 14 (Canceled).

15. (Amended) A chemical mechanical polishing monitoring method, comprising:

sending a drive voltage to a pump, the drive voltage based on a desired volumetric flow rate for a slurry;

delivering, via the pump, the slurry to a polishing pad;

sensing a rotation of the pump;

generating a signal indicative of the rotation of the pump; and

comparing the signal to a threshold signal that is based, in part, on the drive voltage in order to monitor the pump during use;

~~The method of Claim 14,~~ further comprising generating a message based on the comparison.

16-20 (Canceled)